

## 20V P-Channel Enhancement Mode MOSFET

### Description

The NP3415EMR uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

### General Features

- ◆  $V_{DS} = -20V$ ,  $I_D = -4A$   
 $R_{DS(ON)}(\text{Typ.}) = 34m\Omega$  @  $V_{GS} = -4.5V$   
 $R_{DS(ON)}(\text{Typ.}) = 44m\Omega$  @  $V_{GS} = -2.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ ESD Rating: 2500V HBM

### Application

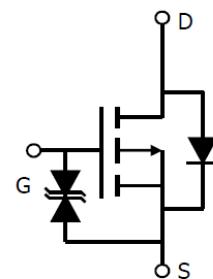
- ◆ PWM applications
- ◆ Load switch

### Package

- ◆ SOT-23-3L

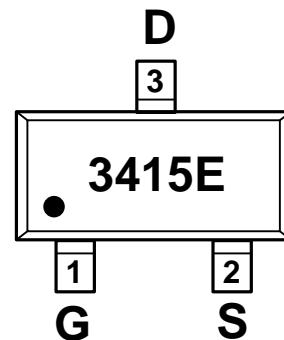


### Schematic diagram



### Marking and pin assignment

SOT-23-3L  
(TOP VIEW)



### Ordering Information

| Part Number | Storage Temperature | Package   | Devices Per Reel |
|-------------|---------------------|-----------|------------------|
| NP3415EMR-G | -55°C to +150°C     | SOT-23-3L | 3000             |

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| parameter                              | symbol   | limit   | unit |
|--|----------|---------|------|
| Drain-source voltage                   | $V_{DS}$ | -20     | V    |
| Gate-source voltage                    | $V_{GS}$ | $\pm 8$ | V    |
| Continuous Drain Current               | $I_D$    | -4      | A    |
|  |          | -3      |      |
| Pulsed Drain Current <sup>C</sup>      | $I_{DM}$ | -20     | A    |
| Maximum power dissipation <sup>B</sup> | $P_D$    | 1.4     | W    |
|  |          | 0.9     |      |
| Operating junction Temperature range   | $T_j$    | -55—150 | °C   |

**Electrical Characteristics** (TA=25°C unless otherwise noted)

| Parameter                                 | Symbol              | Condition   | Min  | Typ   | Max  | Unit |
|---|---------------------|---|------|-------|------|------|
| <b>OFF Characteristics</b>                |                     |   |      |       |      |      |
| Drain-source breakdown voltage            | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA   | -20  | -     | -    | V    |
| Zero gate voltage drain current           | I <sub>DSS</sub>    | V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V  | -    | -     | -1   | μA   |
| Gate-body leakage                         | I <sub>GSS</sub>    | V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V   | -    | -     | ±10  | μA   |
| <b>ON Characteristics</b>                 |                     |   |      |       |      |      |
| Gate threshold voltage                    | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA   | -0.4 | -0.59 | -0.9 | V    |
| Drain-source on-state resistance          | R <sub>DS(ON)</sub> | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A   | -    | 34    | 45   | mΩ   |
|   |                     | V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A   | -    | 44    | 55   |      |
| Forward transconductance                  | g <sub>f</sub>      | V <sub>GS</sub> =-5V, I <sub>D</sub> =-4A   | 8    | -     | -    | S    |
| <b>Dynamic Characteristics</b>            |                     |   |      |       |      |      |
| Input capacitance                         | C <sub>ISS</sub>    | V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V<br>f=1.0MHz  | -    | 751   | -    | pF   |
| Output capacitance                        | C <sub>OSS</sub>    |   | -    | 115   | -    |      |
| Reverse transfer capacitance              | C <sub>RSS</sub>    |   | -    | 80    | -    |      |
| <b>Switching Characteristics</b>          |                     |   |      |       |      |      |
| Turn-on delay time                        | t <sub>D(ON)</sub>  | V <sub>DD</sub> =-10V<br>I <sub>D</sub> =-2.8A<br>V <sub>GEN</sub> =-4.5V<br>R <sub>L</sub> =10ohm<br>R <sub>GEN</sub> =60ohm | -    | 13    | -    | ns   |
| Rise time                                 | tr                  |   | -    | 9     | -    |      |
| Turn-off delay time                       | t <sub>D(OFF)</sub> |   | -    | 19    | -    |      |
| Fall time                                 | tf                  |   | -    | 29    | -    |      |
| Total gate charge                         | Q <sub>g</sub>      | V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A<br>V <sub>GS</sub> =-4.5V  | -    | 9.3   | -    | nC   |
| Gate-source charge                        | Q <sub>gs</sub>     |   | -    | 1     | -    |      |
| Gate-drain charge                         | Q <sub>gd</sub>     |   | -    | 2.2   | -    |      |
| <b>DRAIN-SOURCE DIODE CHARACTERISTICS</b> |                     |   |      |       |      |      |
| Diode forward voltage                     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>s</sub> =-1.25A   | -    | -0.81 | -1.2 | V    |

**Thermal Characteristics**

| Parameter                                  | Symbol       | Typ              | Max | Unit |
|--|--------------|------------------|-----|------|
| Maximum Junction-to-Ambient <sup>A</sup>   | ≤ 10s        | R <sub>θJA</sub> | 70  | 90   |
| Maximum Junction-to-Ambient <sup>A D</sup> | Steady-State |                  | 100 | 125  |
| Maximum Junction-to-Lead <sup>B</sup>      | Steady-State |                  | 63  | 80   |

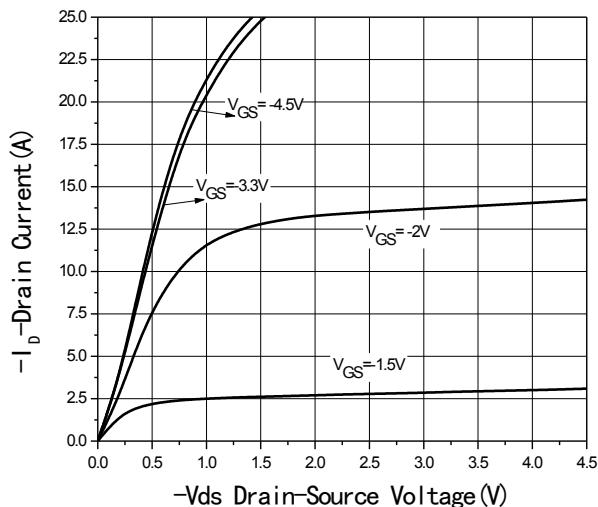
A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using ≤ 10s junction-to-ambient thermal resistance.

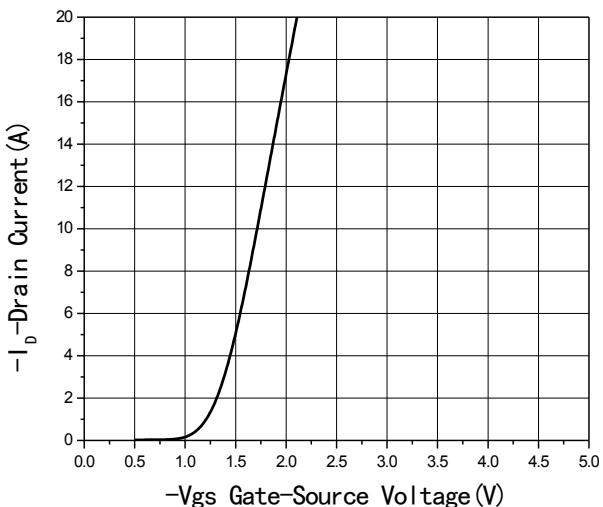
C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C. Ratings are based on low frequency and duty cycles to keep initialTJ=25°C.

D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

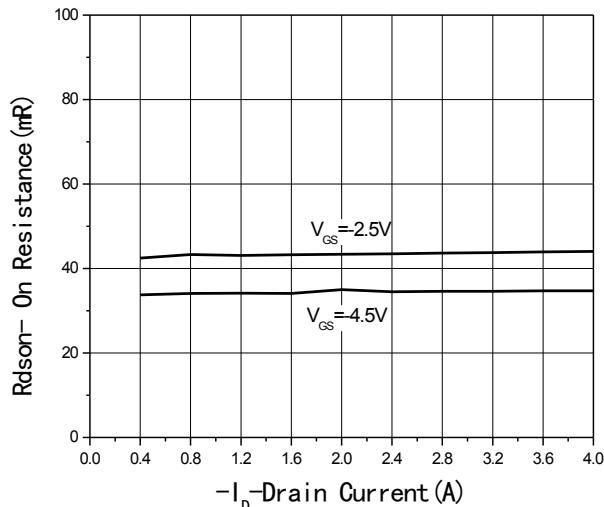
## Typical Performance Characteristics



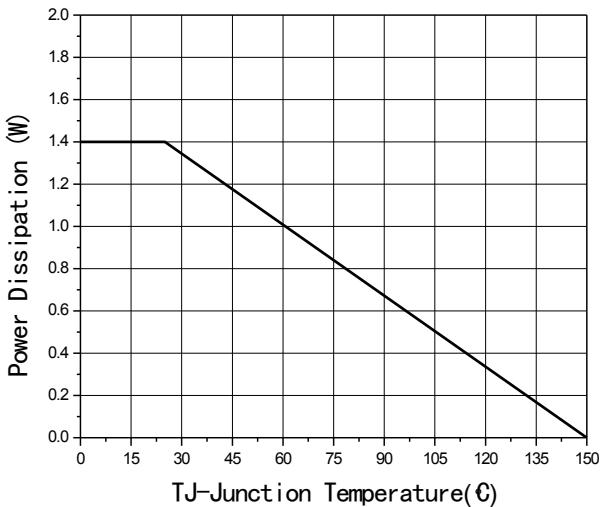
**Fig1 Output Characteristics**



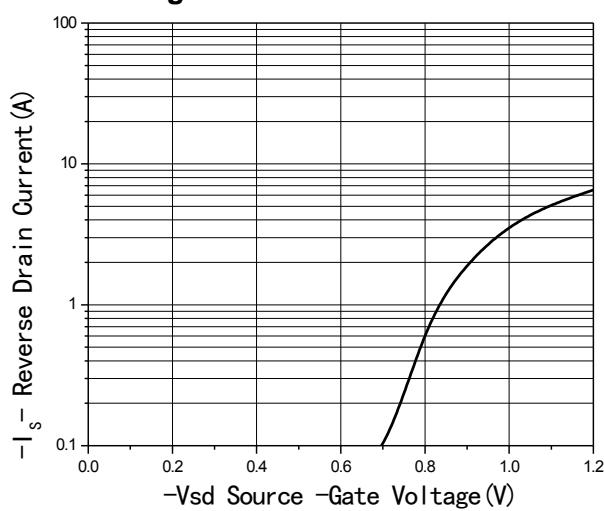
**Fig2 Transfer Characteristics**



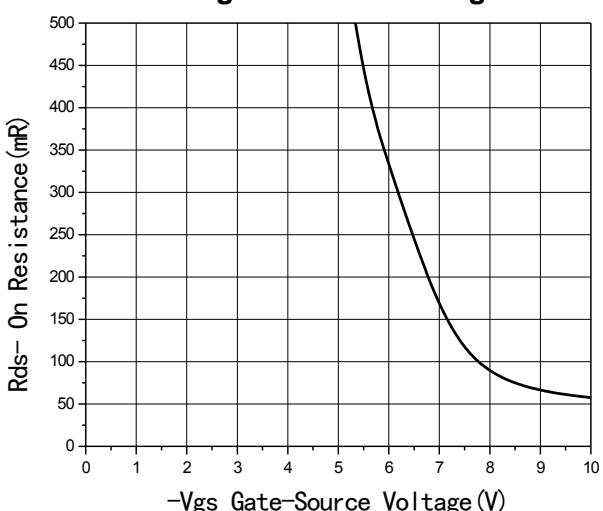
**Fig3 Rdson-Drain current**



**Fig4 Power De-rating**



**Fig5 Source-Drain Diode Forward**



**Fig6 Rdson-Gate drain voltage**

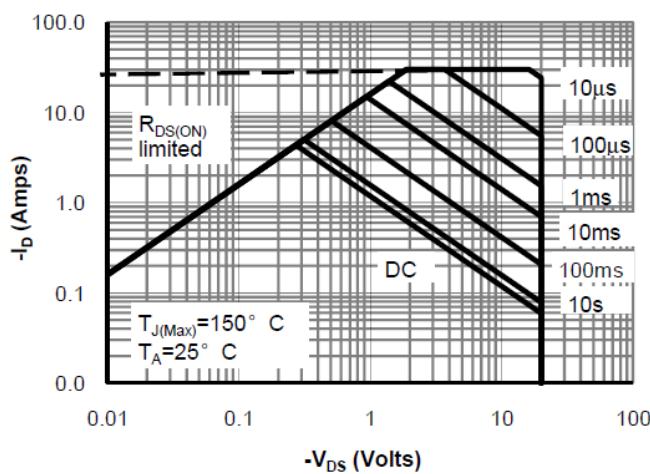


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

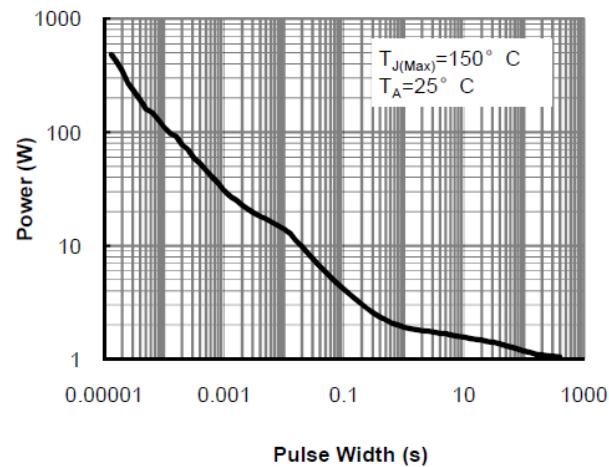


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

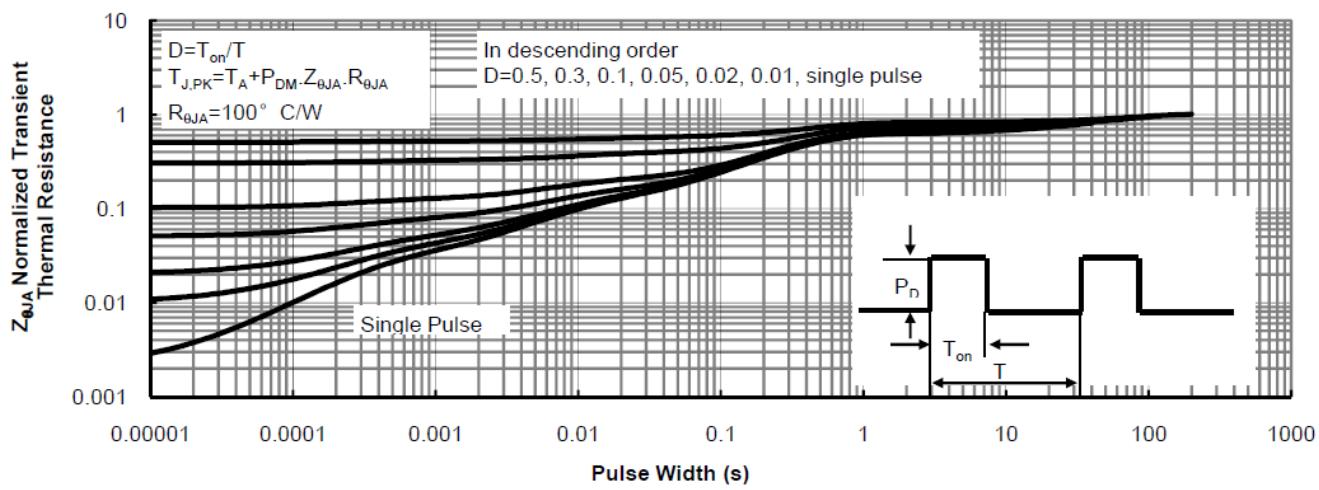
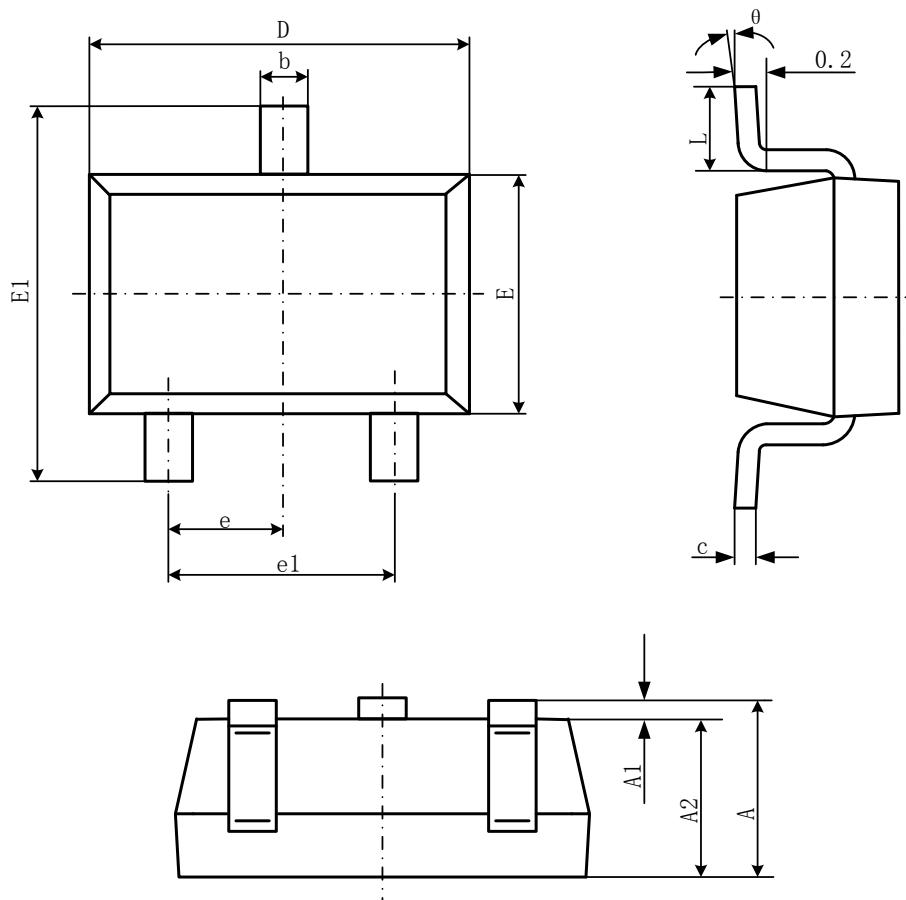


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

## Package Information

- SOT-23-3L



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.050                     | 1.250 | 0.041                | 0.049 |
| A1     | 0.000                     | 0.100 | 0.000                | 0.004 |
| A2     | 1.050                     | 1.150 | 0.041                | 0.045 |
| b      | 0.300                     | 0.500 | 0.012                | 0.020 |
| c      | 0.100                     | 0.200 | 0.004                | 0.008 |
| D      | 2.820                     | 3.020 | 0.111                | 0.119 |
| E      | 1.500                     | 1.700 | 0.059                | 0.067 |
| E1     | 2.650                     | 2.950 | 0.104                | 0.116 |
| e      | 0.950(BSC)                |       | 0.037(BSC)           |       |
| e1     | 1.800                     | 2.000 | 0.071                | 0.079 |
| L      | 0.300                     | 0.600 | 0.012                | 0.024 |
| theta  | 0°                        | 8°    | 0°                   | 8°    |